26NM60SZ-U3

**Preliminary** 

**Power MOSFET** 

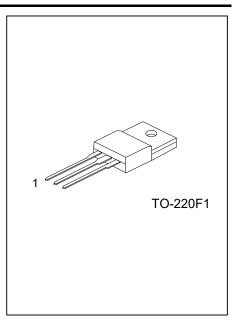
# 26A, 600V N-CHANNEL SUPER-JUNCTION MOSFET

#### **■** DESCRIPTION

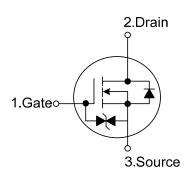
The **UTC 26NM60SZ-U3** is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at AC-DC converters for power applications.

#### ■ FEATURES

- \*  $R_{DS(ON)} \le 0.155 \Omega$  @  $V_{GS}$ =10V,  $I_D$ =8.5A
- \* Fast switching capability
- \* Avalanche energy tested
- \* Improved dv/dt capability, high ruggedness
- \* With ESD Protected: HBM=2KV



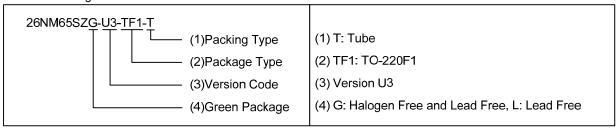
#### ■ SYMBOL



## ■ ORDERING INFORMATION

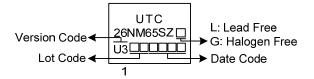
Ordering Number		Daalaaaa	Pin Assignment			De elsieres	
Lead Free	Halogen Free	Package	1	2	3	Packing	
26NM60SZL-U3-TF1-T	26NM60SZG-U3-TF1-T	TO-220F1	G	D	S	Tube	

Note: Pin Assignment: G: Gate D: Drain S: Source



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# ■ MARKING



# ■ **ABSOLUTE MAXIMUM RATINGS** (T<sub>C</sub>=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT	
Drain-Source Voltage		V <sub>DSS</sub>	600	V	
Gate-Source Voltage		$V_{GSS}$	±20	V	
Drain Current	Continuous	I <sub>D</sub>	26	Α	
	Pulsed (Note 2)	I <sub>DM</sub>	78	Α	
Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	62.5	mJ	
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.4	V/ns	
Power Dissipation		P <sub>D</sub>	33	W	
Junction Temperature		TJ	+150	°C	
Storage Temperature		T <sub>STG</sub>	-55 ~ +150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L = 10mH,  $I_{AS}$  = 3.5A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 $\Omega$  Starting  $T_{J}$  = 25 $^{\circ}$ C
- 4.  $I_{SD} \le 26A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$

## **■ THERMAL DATA**

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	$\theta_{JA}$	62.5	°C/W
Junction to Case	θјς	3.79	°C/W

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

# ■ **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub>=25°C, unless otherwise specified)

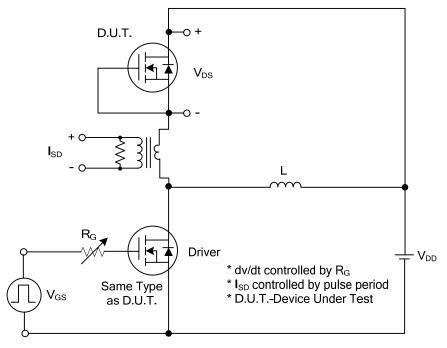
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT			
OFF CHARACTERISTICS									
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	600			V			
Drain-Source Leakage Current	IDSS	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V			1	μΑ			
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±10	μΑ			
ON CHARACTERISTICS									
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	2.5		4.5	V			
Static Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =8.5A			0.155	Ω			
DYNAMIC CHARACTERISTICS									
Input Capacitance	Ciss			1283		pF			
Output Capacitance	Coss	V <sub>GS</sub> =0V, V <sub>DS</sub> =50V, f=1MHz		377		pF			
Reverse Transfer Capacitance	C <sub>RSS</sub>			2		pF			
SWITCHING CHARACTERISTICS									
Total Gate Charge (Note 1)	$Q_{G}$	1/ 400\/ \/ 40\/   0.54		32		nC			
Gate-Source Charge	$Q_{GS}$	V <sub>DS</sub> =480V, V <sub>GS</sub> =10V, I <sub>D</sub> =6.5A		10		nC			
Gate-Drain Charge	$Q_{DD}$	(Note 1, 2)		7		nC			
Turn-On Delay Time (Note 1)	$t_{D(ON)}$			22		ns			
Turn-On Rise Time	$t_R$	V <sub>DD</sub> =100V, V <sub>GS</sub> =10V, I <sub>D</sub> =3A,		21		ns			
Turn-Off Delay Time	$t_{D(OFF)}$	R <sub>G</sub> =25Ω (Note 1, 2)		94		ns			
Turn-Off Fall Time	$t_{F}$			32		ns			
SOURCE- DRAIN DIODE RATINGS AND CH	SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS								
Maximum Continuous Drain-Source Diode	Is				26	Α			
Forward Current	15				20				
Maximum Pulsed Drain-Source Diode	I <sub>SM</sub>				78	Α			
Forward Current									
Drain-Source Diode Forward Voltage (Note 1)	$V_{SD}$	I <sub>S</sub> =26A, V <sub>GS</sub> =0V			1.4	V			
Body Diode Reverse Recovery Time (Note 1)	t <sub>rr</sub>	I <sub>S</sub> =26A, V <sub>GS</sub> =0V,		408		nS			
Body Diode Reverse Recovery Charge	$Q_{rr}$	dI <sub>F</sub> /dt=100A/μs		6274		nC			

Notes: 1. Pulse Test: Pulse width  $\leq$  300µs, Duty cycle  $\leq$  2%.

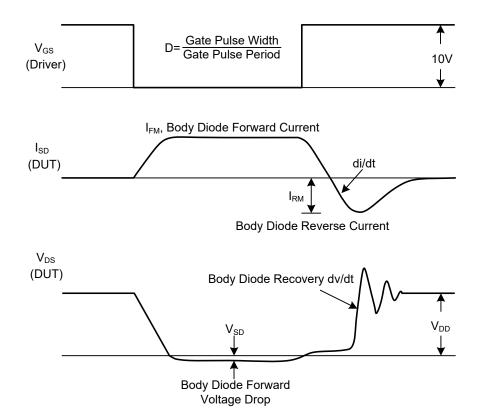
2. Essentially independent of operating temperature.



## **■ TEST CIRCUITS AND WAVEFORMS**

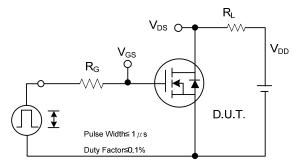


Peak Diode Recovery dv/dt Test Circuit

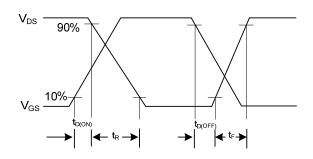


Peak Diode Recovery dv/dt Waveforms

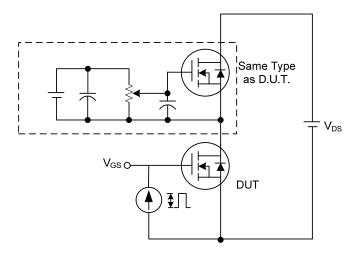
# **■ TEST CIRCUITS AND WAVEFORMS**



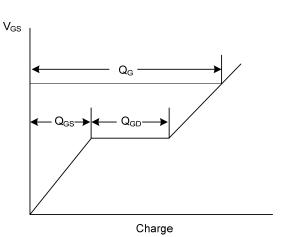
Switching Test Circuit



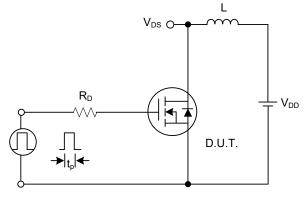
**Switching Waveforms** 



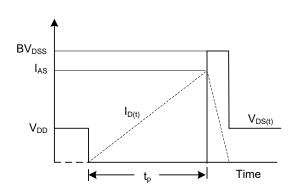
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



**Unclamped Inductive Switching Waveforms** 

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